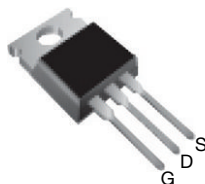


D Series Power MOSFET

TO-220AB


N-Channel MOSFET

PRODUCT SUMMARY

| | | |
|---|-----------------|-----|
| V_{DS} (V) at T_J max. | 450 | |
| $R_{DS(on)}$ max. (Ω) at 25 °C | $V_{GS} = 10$ V | 1.0 |
| Q_g max. (nC) | 18 | |
| Q_{gs} (nC) | 3 | |
| Q_{gd} (nC) | 4 | |
| Configuration | Single | |

FEATURES

- Optimal design
 - Low area specific on-resistance
 - Low input capacitance (C_{iss})
 - Reduced capacitive switching losses
 - High body diode ruggedness
 - Avalanche energy rated (UIS)
- Optimal efficiency and operation
 - Low cost
 - Simple gate drive circuitry
 - Low figure-of-merit (FOM): $R_{on} \times Q_g$
 - Fast switching
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Consumer electronics
 - Displays (LCD or plasma TV)
- Server and telecom power supplies
 - SMPS
- Industrial
 - Welding
 - Induction heating
- Motor drives
- Battery chargers



RoHS*
Available
HALOGEN
FREE
Available

ORDERING INFORMATION

| | |
|---------------------------------|----------------------------|
| Package | TO-220AB |
| Lead (Pb)-free | SiHP6N40D-E3 |
| Lead (Pb)-free and halogen-free | SiHP6N40D-BE3 ^a |
| | SiHP6N40D-GE3 |

Note

a. "BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

| PARAMETER | SYMBOL | LIMIT | UNIT |
|---|------------------|----------------|------|
| Drain-source voltage | V_{DS} | 400 | V |
| Gate-source voltage | V_{GS} | ± 30 | |
| Gate-source voltage AC ($f > 1$ Hz) | | 30 | |
| Continuous drain current ($T_J = 150$ °C) | V_{GS} at 10 V | $T_C = 25$ °C | A |
| | | $T_C = 100$ °C | |
| Pulsed drain current ^a | I_{DM} | 13 | |
| Linear derating factor | | 0.8 | W/°C |
| Single pulse avalanche energy ^b | E_{AS} | 104 | mJ |
| Maximum power dissipation | P_D | 104 | W |
| Operating junction and storage temperature range | T_J, T_{stg} | -55 to +150 | °C |
| Drain-source voltage slope | dV/dt | $T_J = 125$ °C | V/ns |
| Reverse diode dV/dt ^d | | | |
| Soldering recommendations (peak temperature) ^c | For 10 s | 300 | °C |


Notes

- Repetitive rating; pulse width limited by maximum junction temperature
- $V_{DS} = 50$ V, starting $T_J = 25$ °C, $L = 2.3$ mH, $R_g = 25$ Ω , $I_{AS} = 9.5$ A
- 1.6 mm from case
- $I_{SD} \leq I_D$, starting $T_J = 25$ °C

**THERMAL RESISTANCE RATINGS**

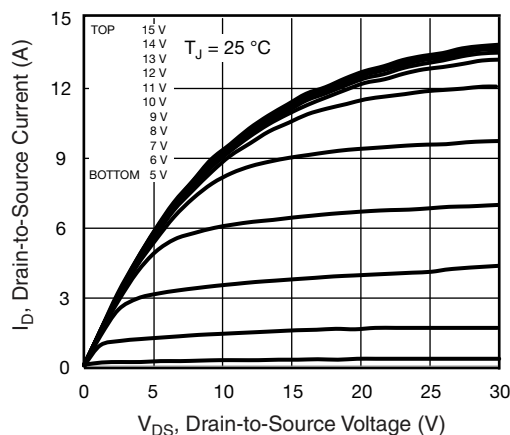
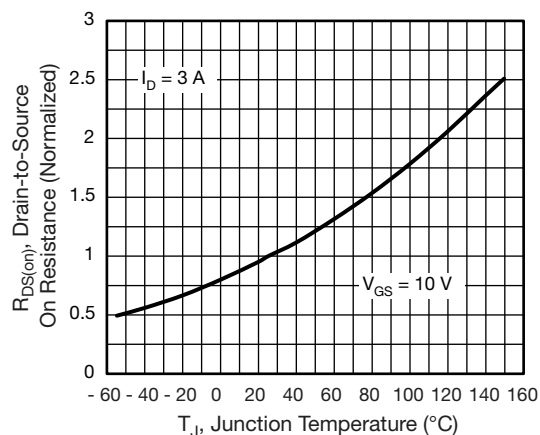
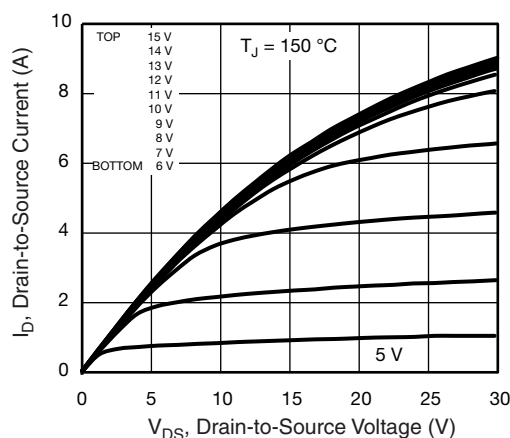
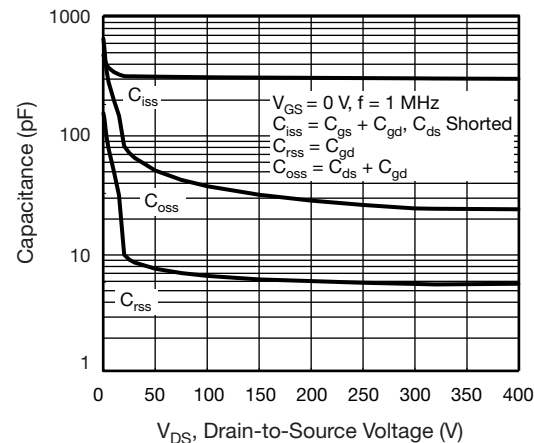
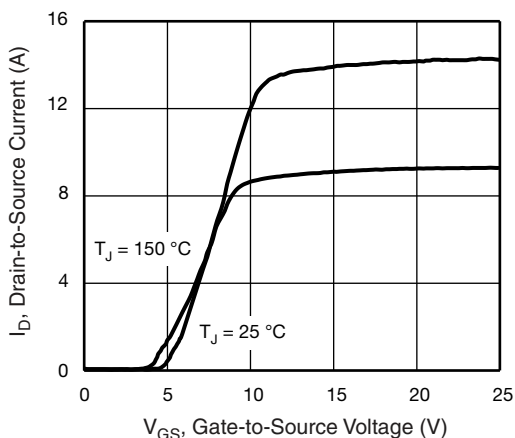
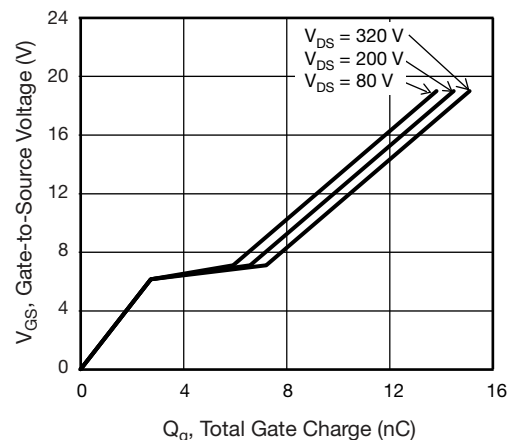
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum junction-to-ambient | R_{thJA} | - | 62 | °C/W |
| Maximum junction-to-case (drain) | R_{thJC} | - | 1.2 | |

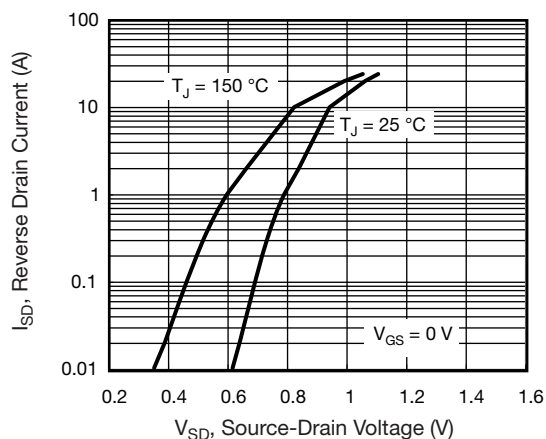
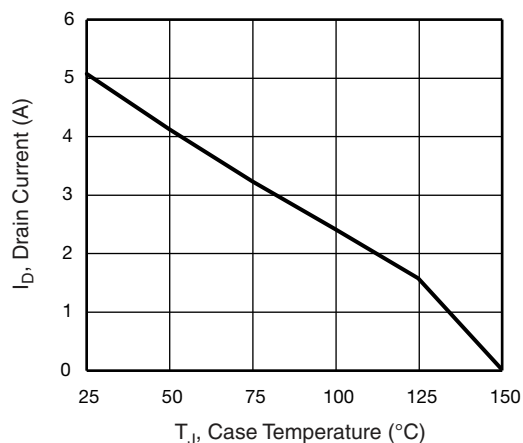
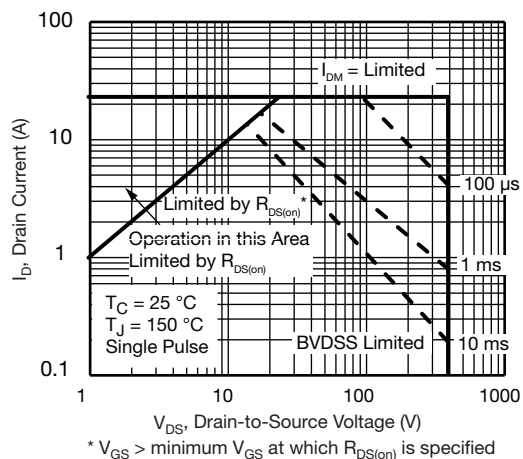
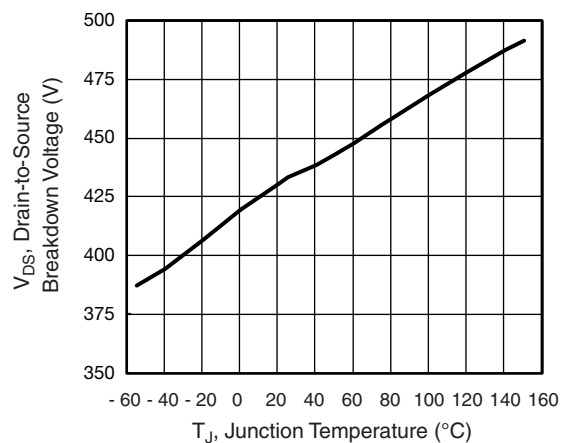
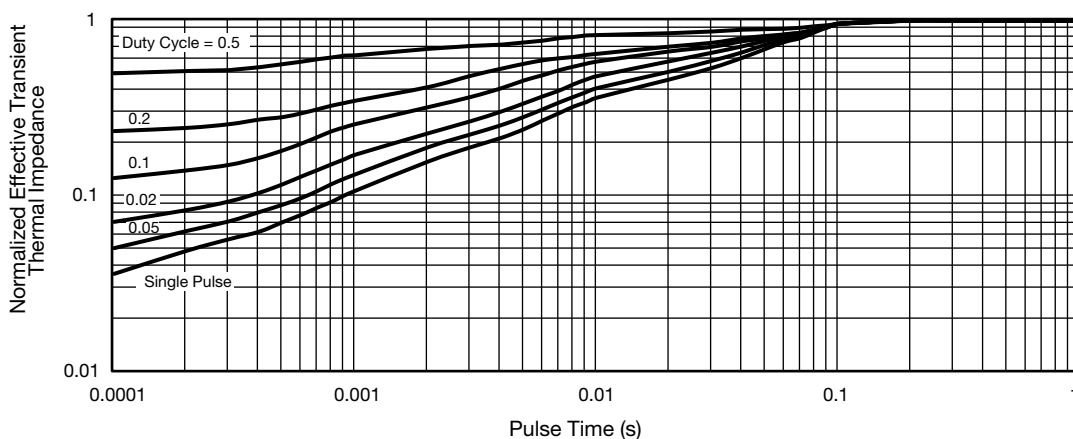
SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

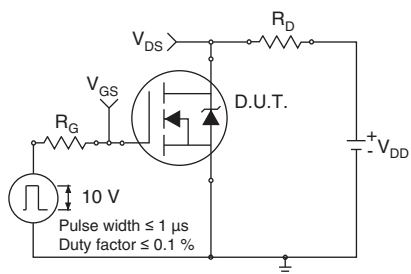
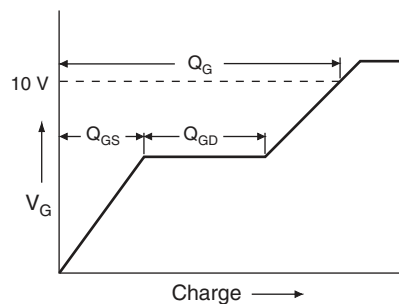
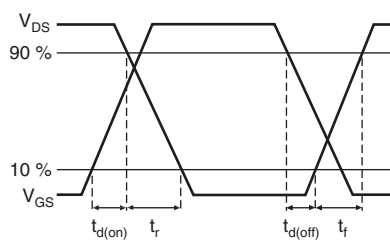
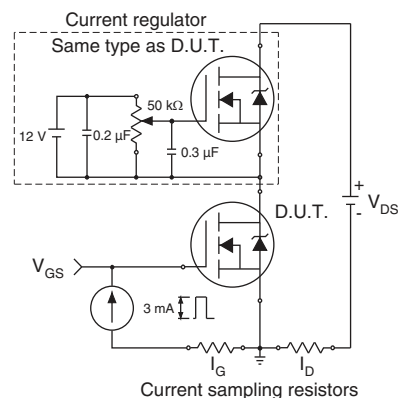
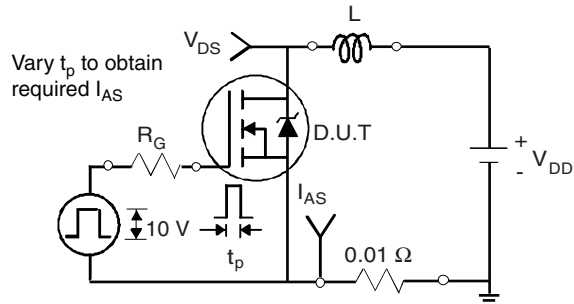
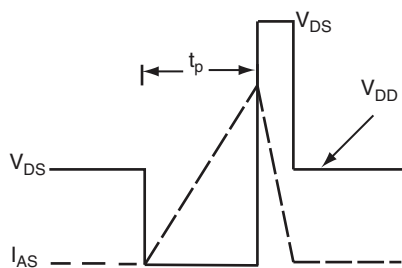
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
|---|----------------------------------|--|---|------|------|-------|------|
| Static | | | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = 0 V, I _D = 250 μA | | 400 | - | - | V |
| V _{DS} temperature coefficient | ΔV _{DS} /T _J | Reference to 25 °C, I _D = 250 μA | | - | 0.53 | - | V/°C |
| Gate-source threshold Voltage (N) | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | | 3 | - | 5 | V |
| Gate-source leakage | I _{GSS} | V _{GS} = ± 30 V | | - | - | ± 100 | nA |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 400 V, V _{GS} = 0 V | | - | - | 1 | μA |
| | | V _{DS} = 320 V, V _{GS} = 0 V, T _J = 125 °C | | - | - | 10 | |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 3 A | - | 0.85 | 1.0 | Ω |
| Forward transconductance | g _{fs} | V _{DS} = 50 V, I _D = 3 A | | - | 1.7 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz | | - | 311 | - | pF |
| Output capacitance | C _{oss} | | | - | 38 | - | |
| Reverse transfer capacitance | C _{rss} | | | - | 7 | - | |
| Effective output capacitance, energy related ^a | C _{o(er)} | V _{GS} = 0 V, V _{DS} = 0 V to 320 V | | - | 44 | - | |
| Effective output capacitance, time related ^b | C _{o(tr)} | | | - | 54 | - | |
| Total gate charge | Q _g | V _{GS} = 10 V | I _D = 3 A, V _{DS} = 320 V | - | 9 | 18 | nC |
| Gate-source charge | Q _{gs} | | | - | 3 | - | |
| Gate-drain charge | Q _{gd} | | | - | 4 | - | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 400 V, I _D = 3 A, V _{GS} = 10 V, R _g = 9.1 Ω | | - | 12 | 24 | ns |
| Rise time | t _r | | | - | 11 | 22 | |
| Turn-off delay time | t _{d(off)} | | | - | 14 | 28 | |
| Fall time | t _f | | | - | 8 | 16 | |
| Gate input resistance | R _g | f = 1 MHz, open drain | | 1.0 | 1.9 | 3.8 | Ω |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 6 | A |
| Pulsed diode forward current | I _{SM} | | | - | - | 24 | |
| Diode forward voltage | V _{SD} | T _J = 25 °C, I _S = 3 A, V _{GS} = 0 V | | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | T _J = 25 °C, I _F = I _S = 3 A, dI/dt = 100 A/μs, V _R = 20 V | | - | 236 | - | ns |
| Reverse recovery charge | Q _{rr} | | | - | 1.1 | - | μC |
| Reverse recovery current | I _{RRM} | | | - | 9 | - | A |

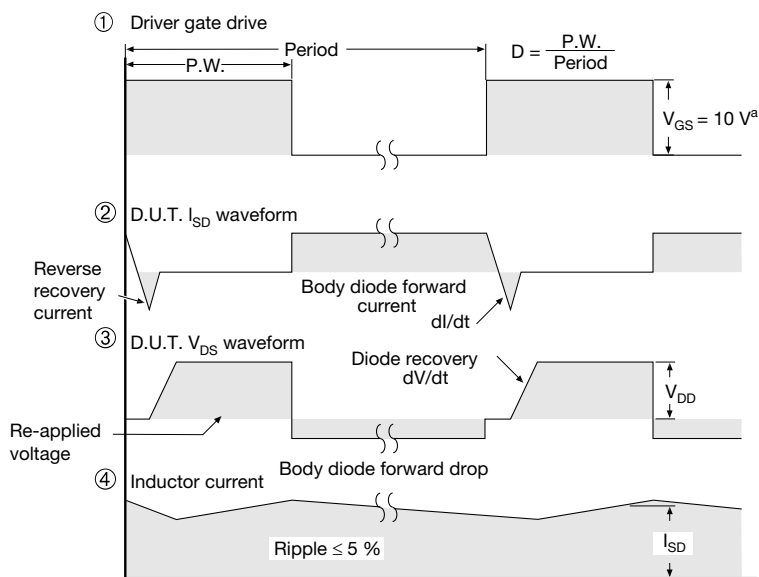
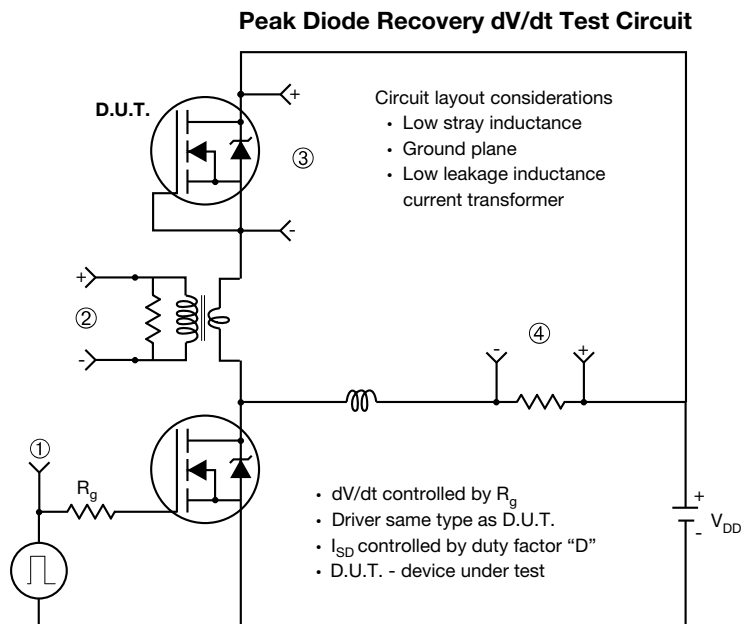
Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage


Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 9 - Maximum Drain Current vs. Case Temperature

Fig. 8 - Maximum Safe Operating Area

Fig. 10 - Temperature vs. Drain-to-Source Voltage

Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case


Fig. 12 - Switching Time Test Circuit

Fig. 16 - Basic Gate Charge Waveform

Fig. 13 - Switching Time Waveforms

Fig. 17 - Gate Charge Test Circuit

Fig. 14 - Unclamped Inductive Test Circuit

Fig. 15 - Unclamped Inductive Waveforms


Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 18 - For N-Channel

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